 State-of-the-Art BiCMOS Design Significantly Reduces I_{CCZ} 	D OR N PACKAGE (TOP VIEW)
 3-State Outputs Drive Bus Lines or Buffer-Memory Address Registers 	
 ESD Protection Exceeds 2000 V Per MIL-STD-883 Method 3015 	1A 2 13 4OE 1Y 3 12 4A 2OE 4 11 4Y
 High-Impedance State During Power Up and Power Down 	$2OE \begin{bmatrix} 4 \\ 10 \end{bmatrix} 47$ $2A \begin{bmatrix} 5 \\ 10 \end{bmatrix} 3OE$ $2Y \begin{bmatrix} 6 \\ 9 \end{bmatrix} 3A$
 Package Options Include Plastic Small-Outline (D) and Standard Plastic 300-mil DIPs (N) 	GND [7 8] 3Y

description

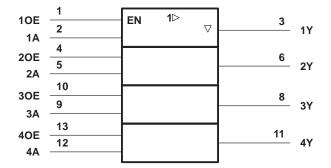
The SN64BCT126A bus buffer features independent line drivers with 3-state outputs. Each output is disabled when the associated output-enable (OE) input is low.

The SN64BCT126A is characterized for operation from – 40°C to 85°C and 0°C to 70°C.

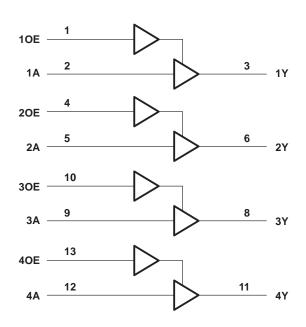
(each buffer)								
INPU	JTS	OUTPUT						
OE	Α	Y						
Н	Н	Н						
н	L	L						
L	Х	Z						

FUNCTION TABLE

logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



logic diagram (positive logic)



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SN64BCT126A QUADRUPLE BUS BUFFER GATE WITH 3-STATE OUTPUTS

SCBS051C - AUGUST 1990 - REVISED JULY 1998

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input voltage range, V _I (see Note 1)	
Voltage range applied to any output in the disabled or power-off state, VO	0.5 V to 5.5 V
Voltage range applied to any output in the high state, VO	-0.5 V to V _{CC}
Current into any output in the low state, I _O	128 mA
Package thermal impedance, θ_{JA} (see Note 2): D package	127°C/W
N package	
Storage temperature range, T _{stg} –6	5°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input negative voltage rating may be exceeded if the input clamp current rating is observed.

2. The package thermal impedance is calculated in acordane with JESD 51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

		MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	V
VIH	High-level input voltage	2			V
VIL	Low-level input voltage			0.8	V
Iк	Input clamp current			-18	mA
IOH	High-level output current			-15	mA
I _{OL}	Low-level output current			64	mA
TA	Operating free-air temperature	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



SN64BCT126A QUADRUPLE BUS BUFFER GATE WITH 3-STATE OUTPUTS SCBS051C - AUGUST 1990 - REVISED JULY 1998

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TES	T CONDITIONS	MIN	түр†	MAX	UNIT
VIK	$V_{CC} = 4.5 V,$	Ij = -18 mA			-1.2	V
Vou		$I_{OH} = -3 \text{ mA}$	2.4	3.3		V
VOH	$V_{CC} = 4.5 V$	I _{OH} = –15 mA	2	3.1		v
VOL	$V_{CC} = 4.5 V,$	I _{OH} = 64 mA		0.42	0.55	V
IOZH	V _{CC} = 5.5 V,	$V_{O} = 2.7 V$			50	μA
IOZL	V _{CC} = 5.5 V,	$V_{O} = 0.5 V$			-50	μA
107	$V_{CC} = 0$ to 1.3 V (power up)	V _O = 2.7 V or 0.5 V, OE at 2 V			±50	
IOZ	V_{CC} = 1.3 V to 0 (power down)	0 = 2.7 v or 0.5 v, $0 = 2.7$			±50	μA
l	$V_{CC} = 0,$	$V_{I} = 7 V$			0.1	mA
IН	V _{CC} = 5.5 V,	V _I = 2.7 V			25	μA
١ _{IL}	V _{CC} = 5.5 V,	V _I = 0.5 V			-20	μA
los‡	V _{CC} = 5.5 V,	$V_{O} = 0$	-100		-225	mA
ICCL	$V_{CC} = 5.5 V$			35	51	mA
Іссн	$V_{CC} = 5.5 V$			21	33	mA
ICCZ	V _{CC} = 5.5 V			5	10	mA
C _i	V _{CC} = 5 V,	$V_{I} = 2.5 \text{ V or } 0.5 \text{ V}$		4		pF
Co	V _{CC} = 5 V,	V _O = 2.5 V or 0.5 V		9		pF

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$. [‡] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

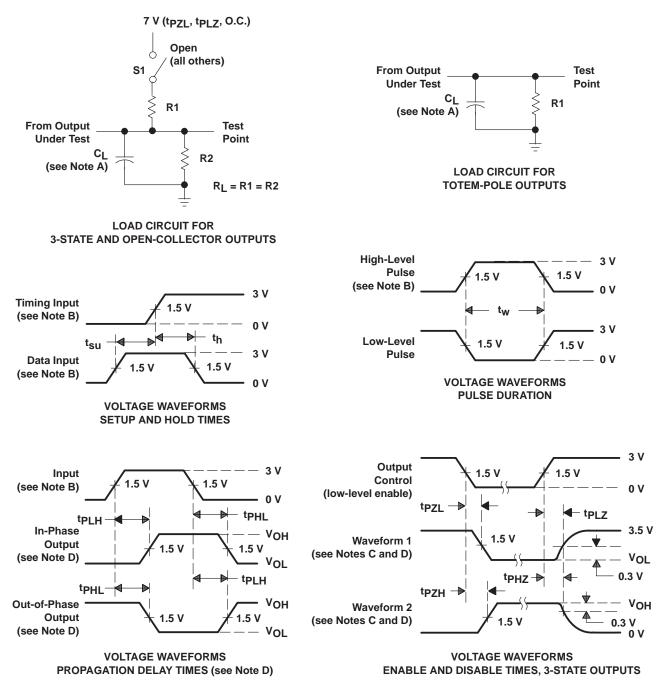
switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	CL R1	C = 5 V, = 50 pF = 500 Ω = 500 Ω	; <u>)</u> ,	CL R1 R2	= 50 pF = 500 Ω = 500 Ω	<u>),</u> <u>)</u>		UNIT
		(001101)	$T_{A} = 25^{\circ}C$			T _A = −40 °C to 85°C		T _A = 0°C to 70°C		
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
^t PLH	А	Y	1.5	3.6	4.9	1.5	6.3	1.5	6.3	ns
^t PHL	A	I	2.7	5.3	6.9	2.7	7.7	2.7	7.4	115
^t PZH	OE	Y	2.6	4.8	6.4	2.6	7.9	2.6	7.9	ns
^t PZL	OE	I	3.7	6.4	8.3	3.7	10.5	3.7	10	115
^t PHZ	OE	Y	3.2	6.6	8.2	3.2	10	3.2	10	ns
^t PLZ	0L	I	3.4	6.5	8	3.4	12.3	3.4	10.7	115



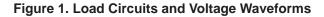
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PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, t_f = t_f \leq 2.5 ns, duty cycle = 50%.
- C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- D. The outputs are measured one at a time with one transition per measurement.
- E. When measuring propagation delay times of 3-state outputs, switch S1 is open.







6-Feb-2020

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
SN64BCT126AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	6BCT126A	Samples
SN64BCT126ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	DCT126A	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

6-Feb-2020

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



1	All dimensions are nominal												
	Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	· /	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
	SN64BCT126ANSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TEXAS INSTRUMENTS

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PACKAGE MATERIALS INFORMATION

10-Aug-2016



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN64BCT126ANSR	SO	NS	14	2000	367.0	367.0	38.0

MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0°-10° Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.





NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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